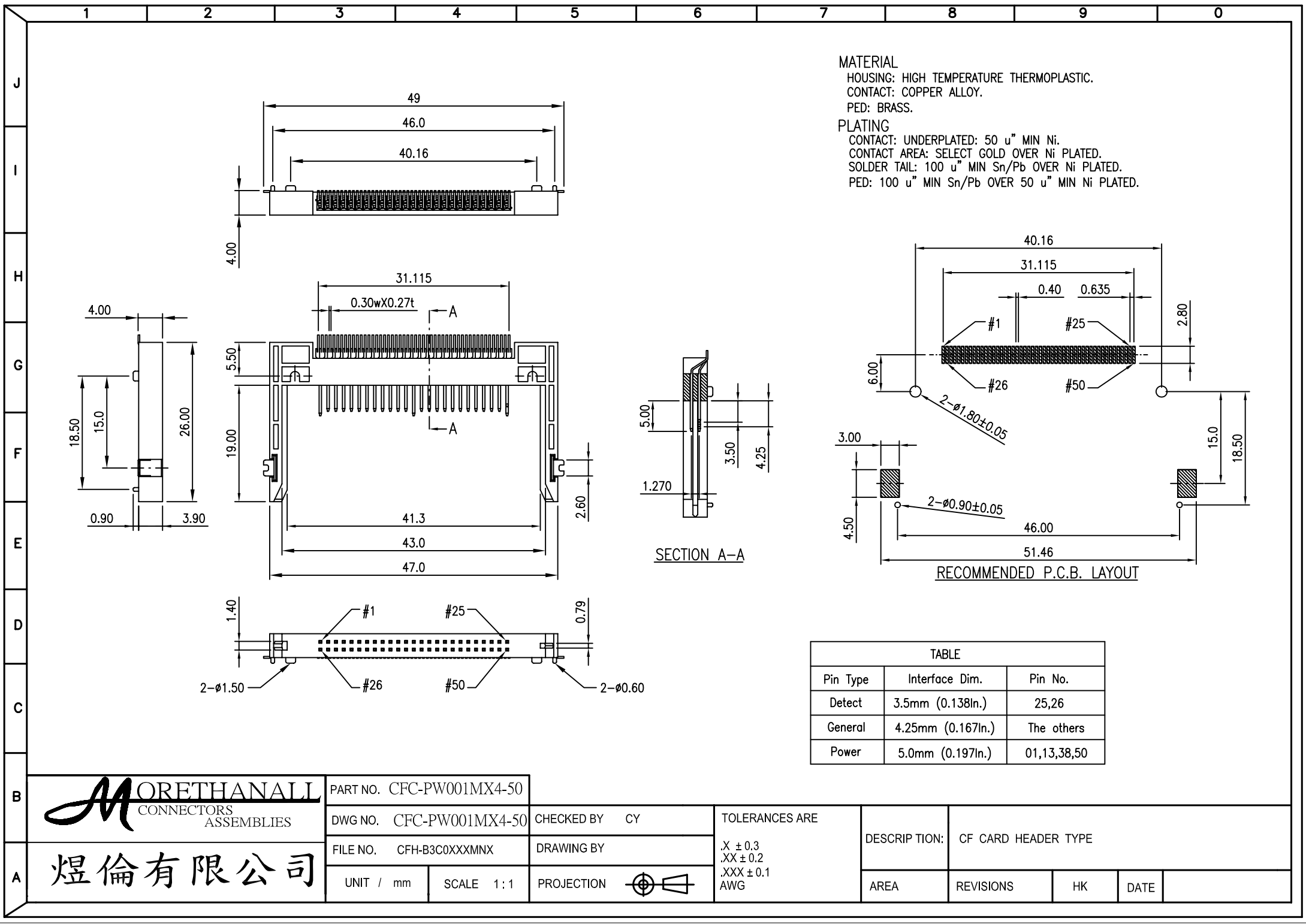




MATERIAL
HOUSING: HIGH TEMPERATURE THERMOPLASTIC.
CONTACT: COPPER ALLOY.
PED: BRASS.
PLATING
CONTACT: UNDERPLATED: 50 u" MIN Ni.
CONTACT AREA: SELECT GOLD OVER Ni PLATED.
SOLDER TAIL: 100 u" MIN Sn/Pb OVER Ni PLATED.
PED: 100 u" MIN Sn/Pb OVER 50 u" MIN Ni PLATED.

TABLE		
Pin Type	Interface Dim.	Pin No.
Detect	3.5mm (0.138In.)	25,26
General	4.25mm (0.167In.)	The others
Power	5.0mm (0.197In.)	01,13,38,50

MORETHANALL
CONNECTORS
ASSEMBLIES

PART NO. CFC-PW001MX4-50

DWG NO. CFC-PW001MX4-50

FILE NO. CFH-B3C0XXXMNX

CHECKED BY CY

DRAWING BY

TOLERANCES ARE

.X ± 0.3
.XX ± 0.2
.XXX ± 0.1
AWG

DESCRIP TION: CF CARD HEADER TYPE

煜倫有限公司

UNIT / mm SCALE 1:1

PROJECTION

AREA REVISIONS HK DATE